

FIG.1

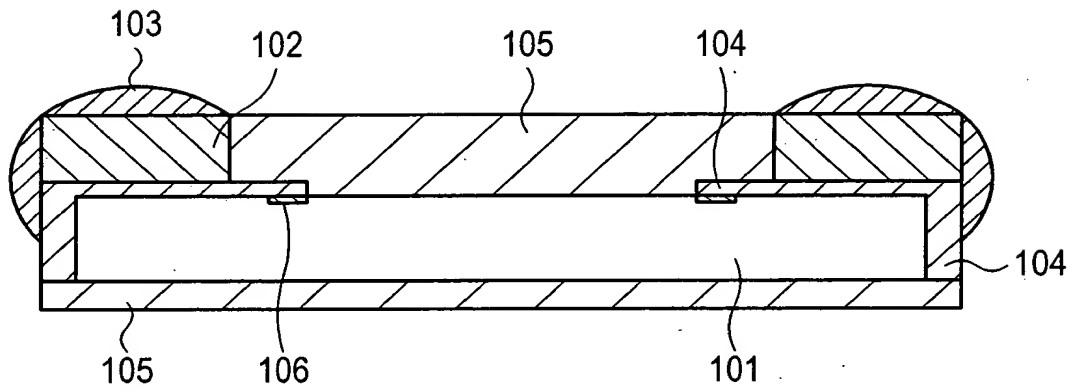


FIG.2

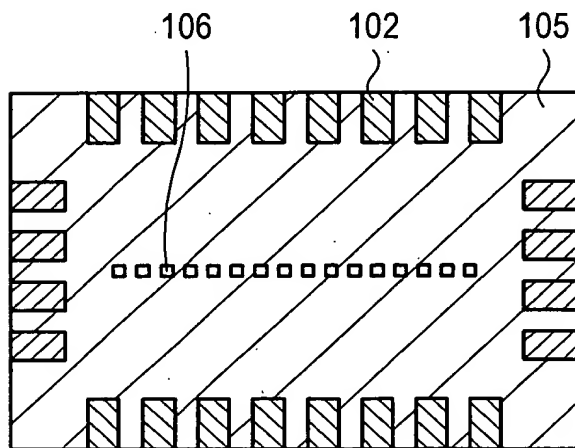


FIG.3

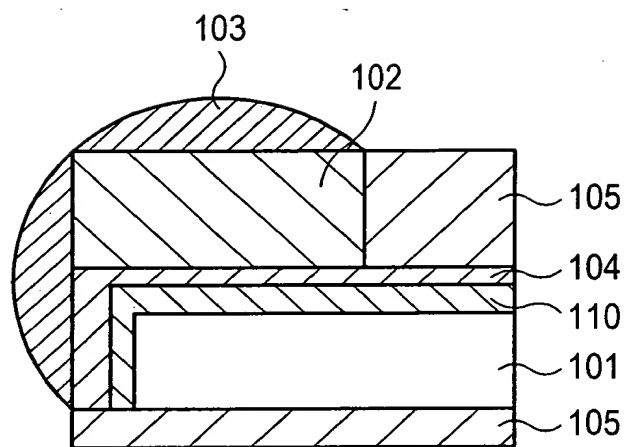


FIG.4

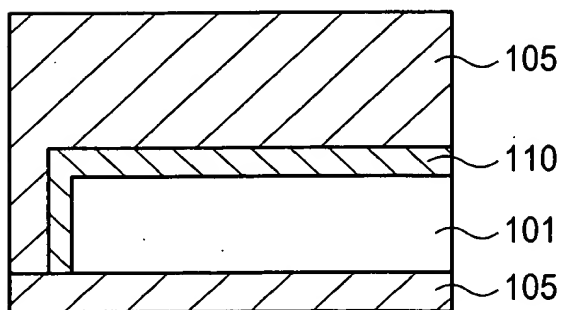
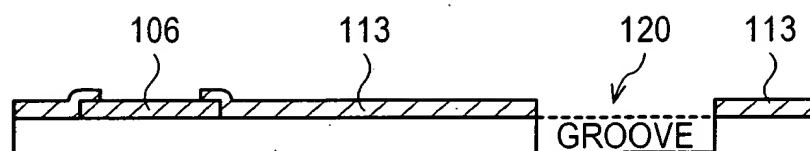
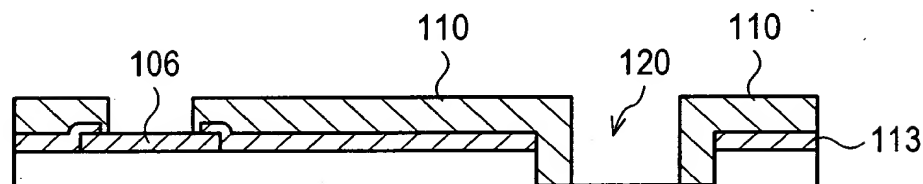
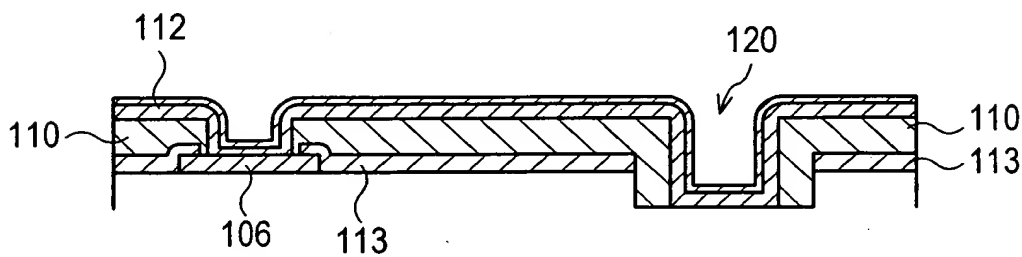


FIG.5(a)

FORMING OF GROOVE

**FIG.5(b)**

FORMING OF INSULATING LAYER

**FIG.5(c)**

FORMING OF METAL FILM



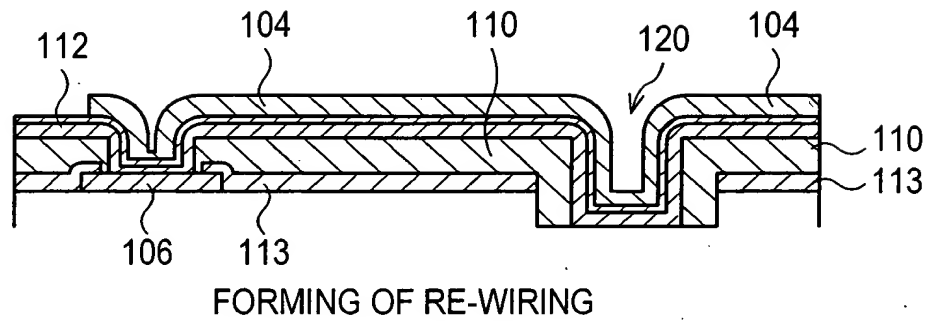
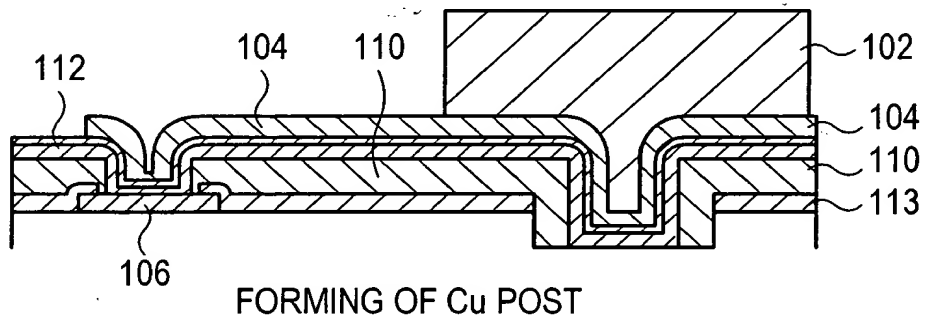
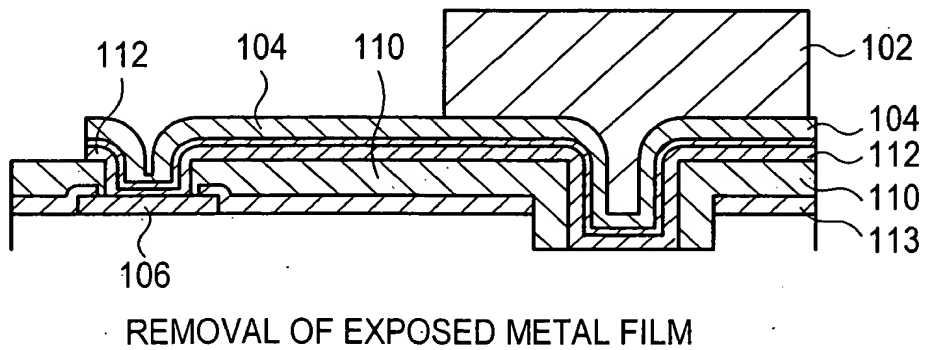
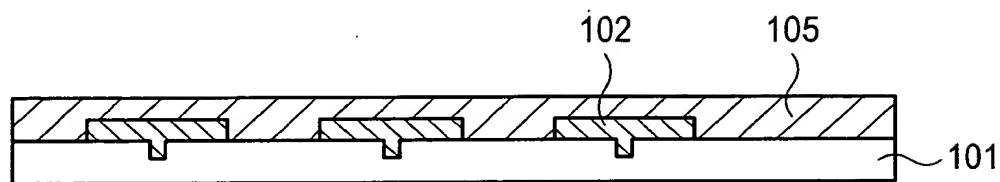
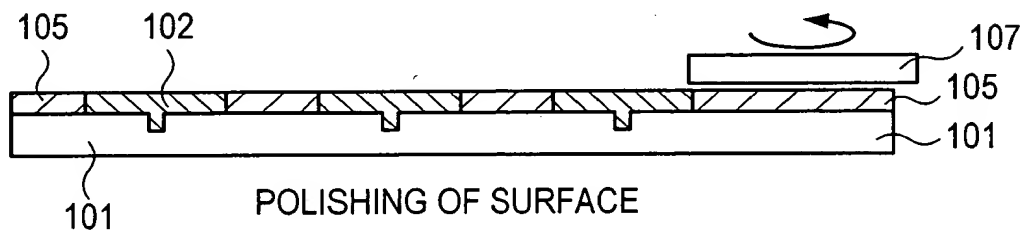
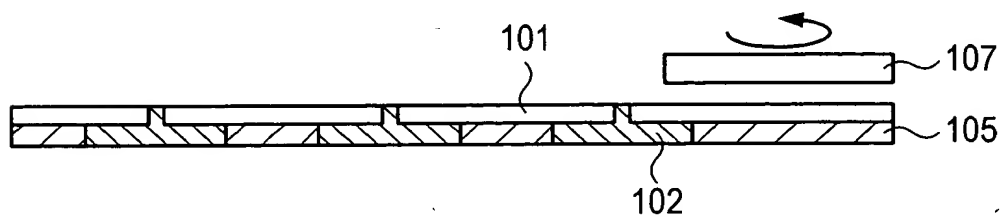
FIG.5(d)**FIG.5(e)****FIG.5(f)**

FIG.6(a)

SEALING WITH RESIN

**FIG.6(b)**

POLISHING OF SURFACE

**FIG.6(c)**

POLISHING OF BACK SIDE



FIG.6(d)

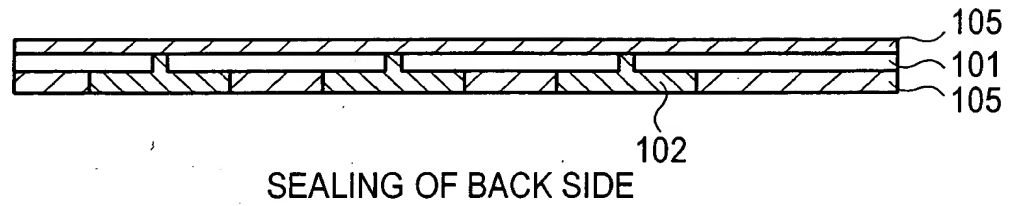


FIG.6(e)

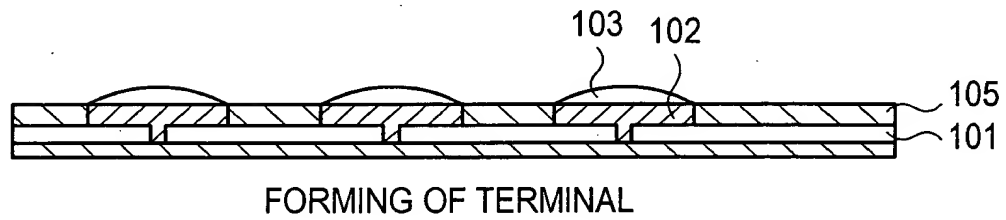


FIG.6(f)

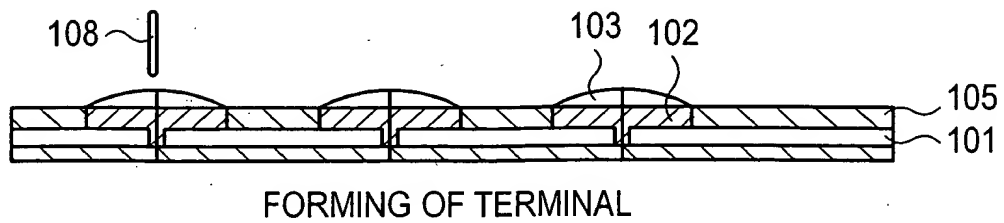


FIG.7(a)

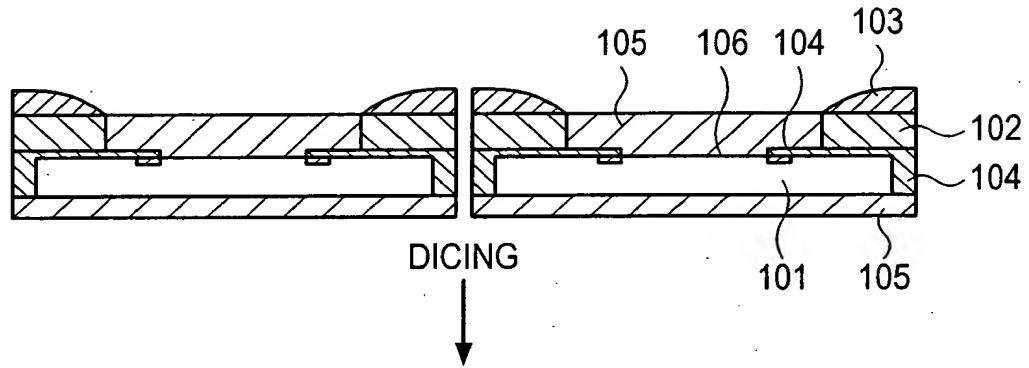


FIG.7(b)

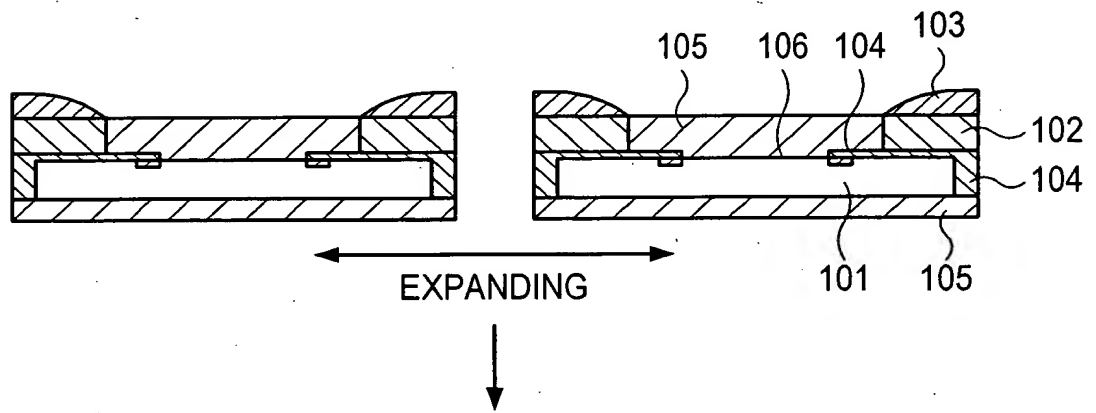


FIG.7(c)

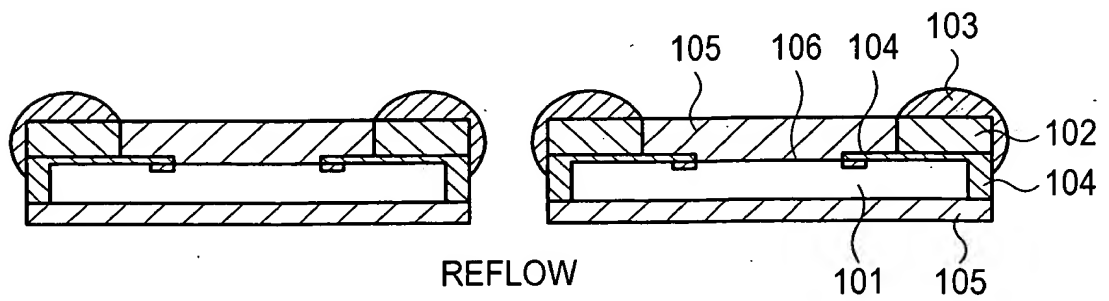


FIG.8

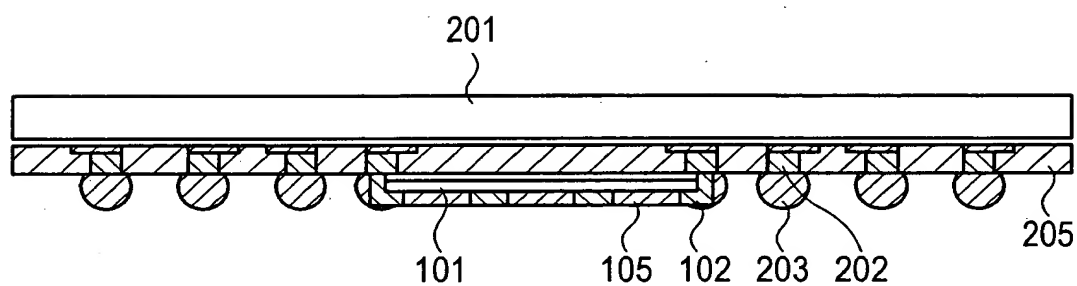


FIG.9

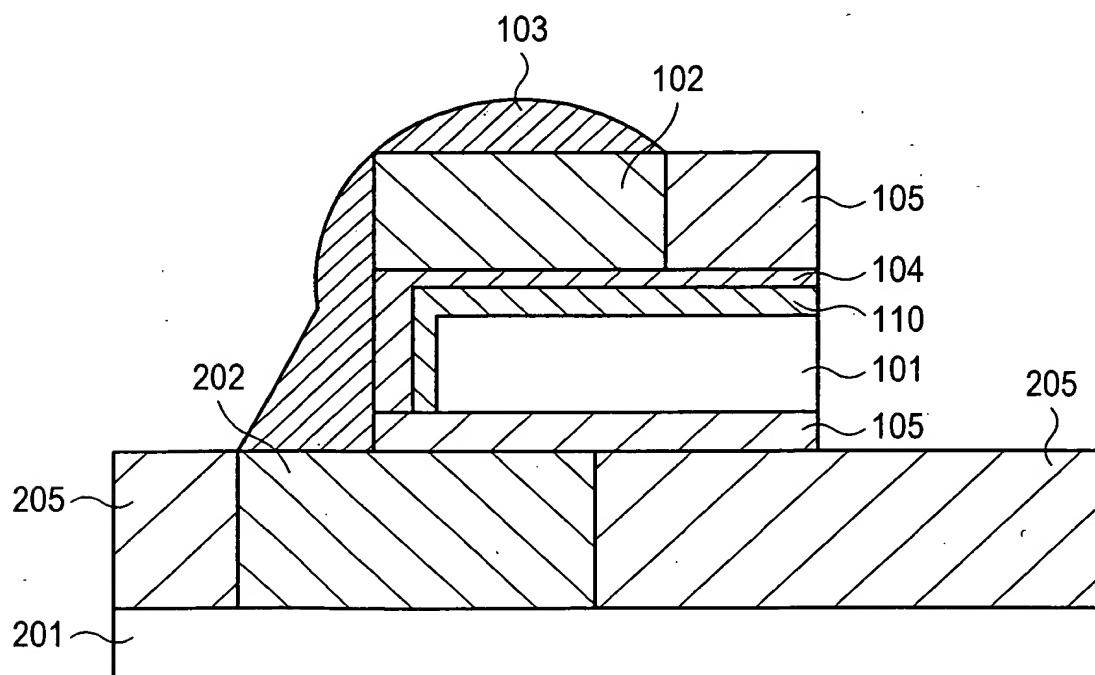


FIG.10

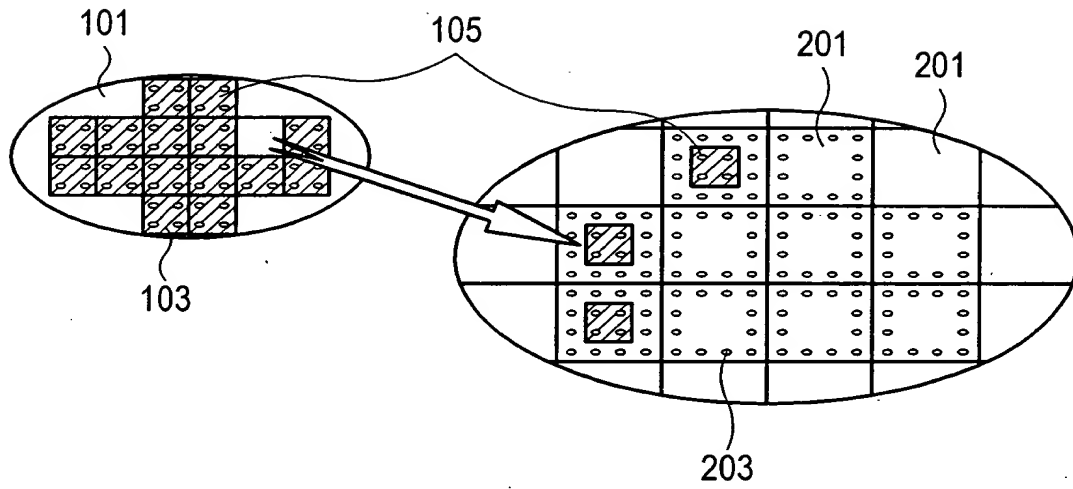


FIG.11

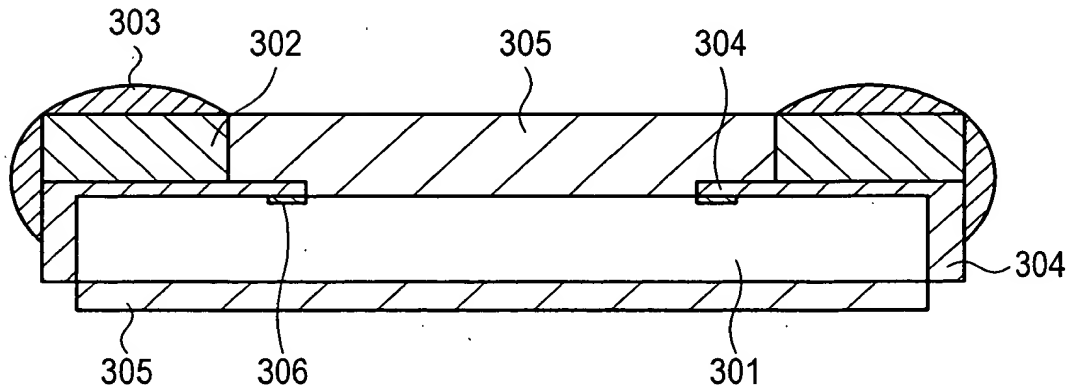


FIG.12

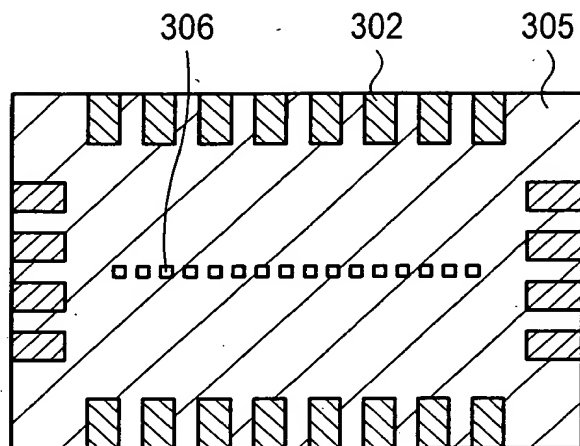


FIG.13

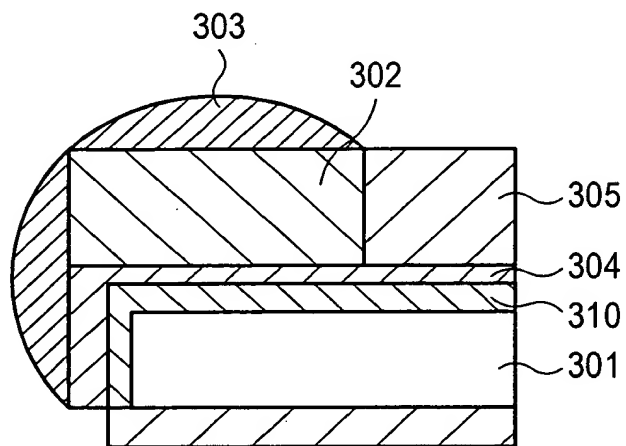


FIG.14

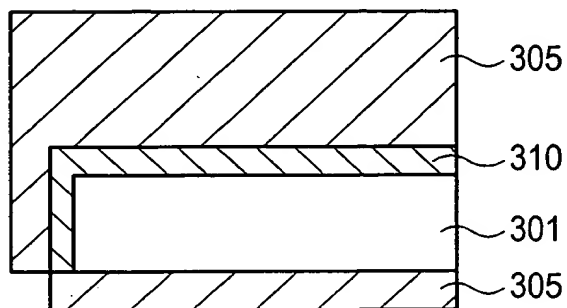
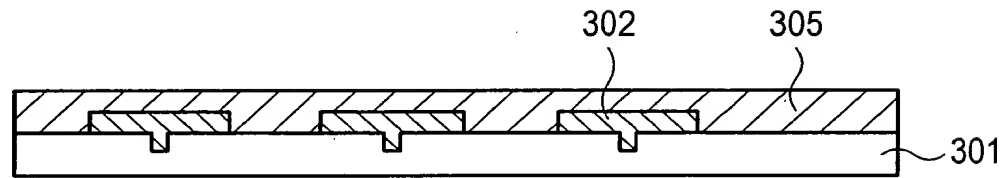
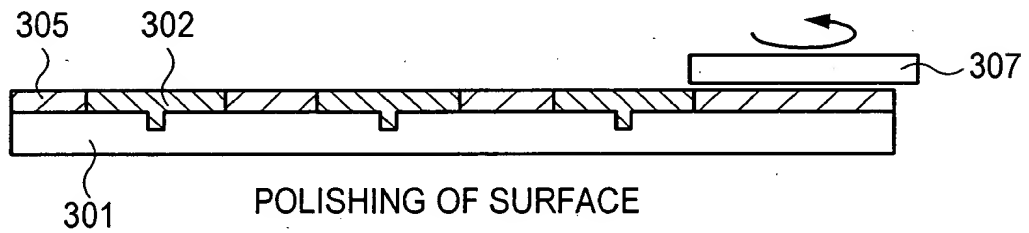
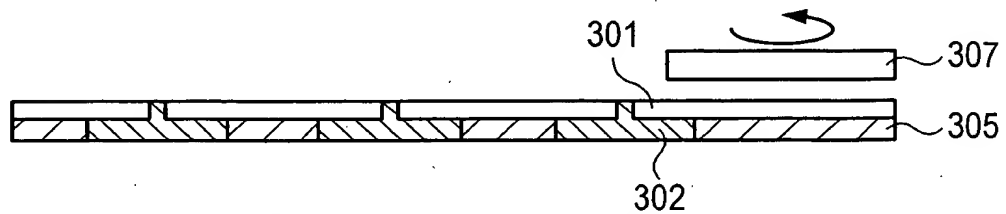


FIG.15(a)

SEALING WITH RESIN

**FIG.15(b)**

POLISHING OF SURFACE

**FIG.15(c)**

POLISHING OF BACK SIDE



FIG.15(d)

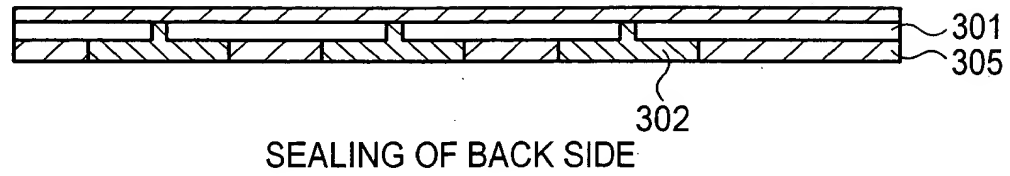


FIG.15(e)

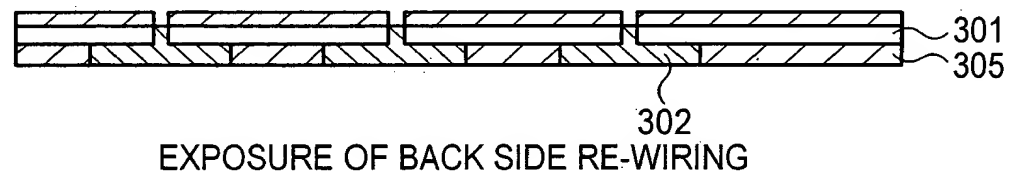


FIG.15(f)

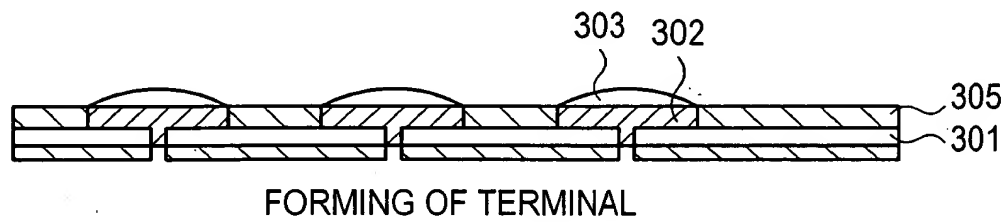


FIG.15(g)

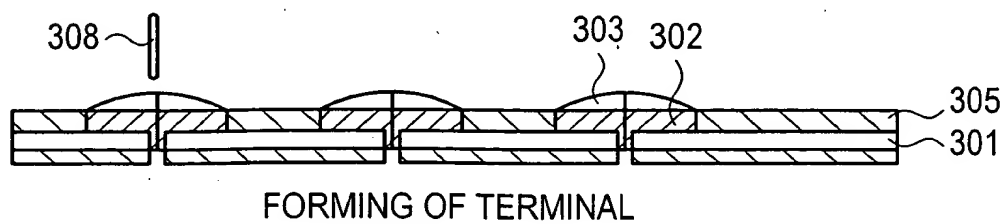


FIG.16(b)

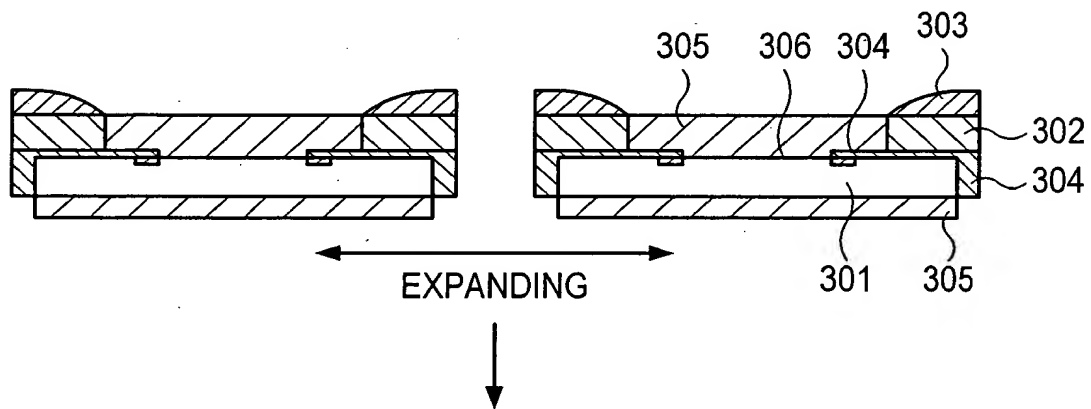


FIG.16(c)

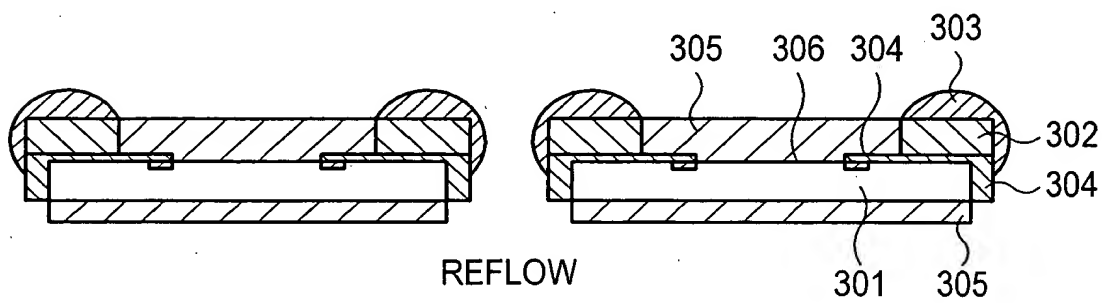


FIG.17

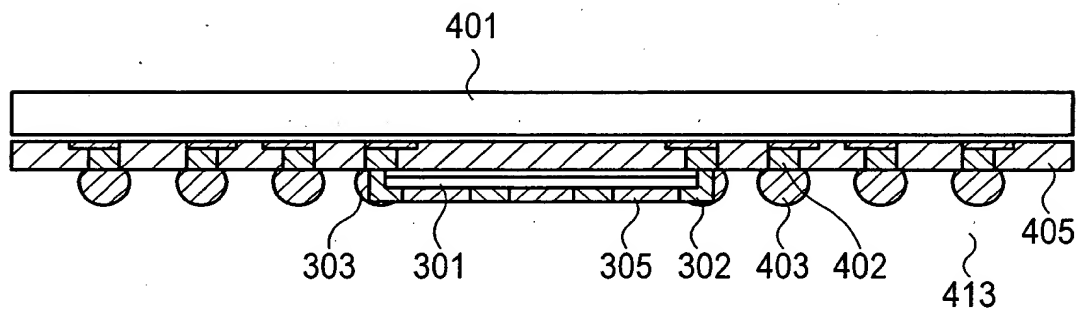


FIG.18

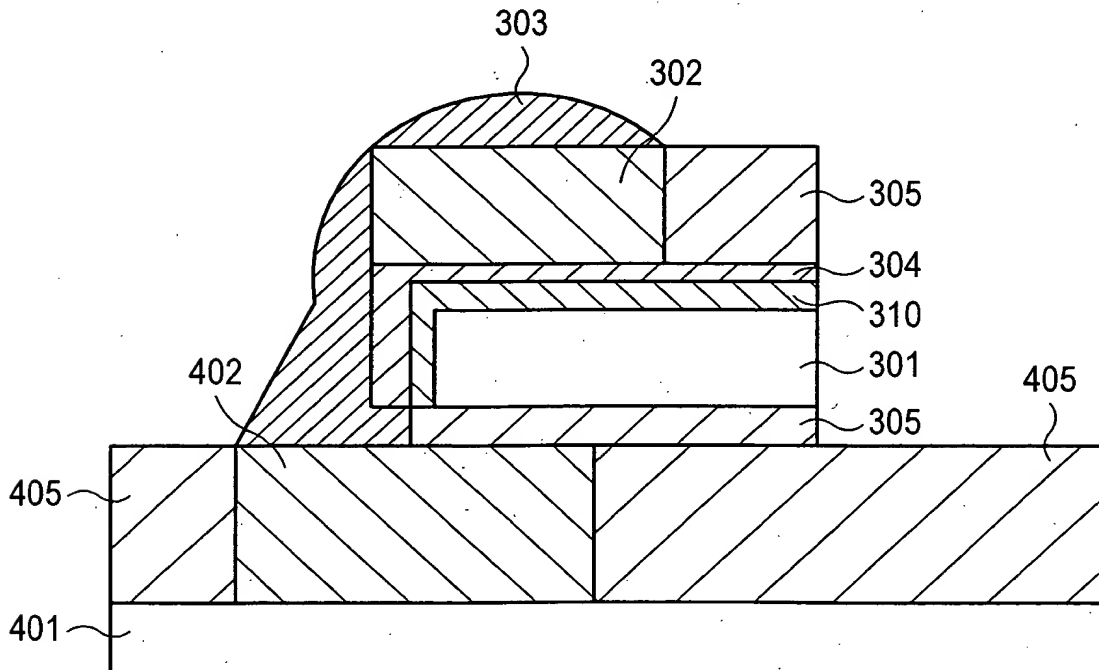


FIG.19

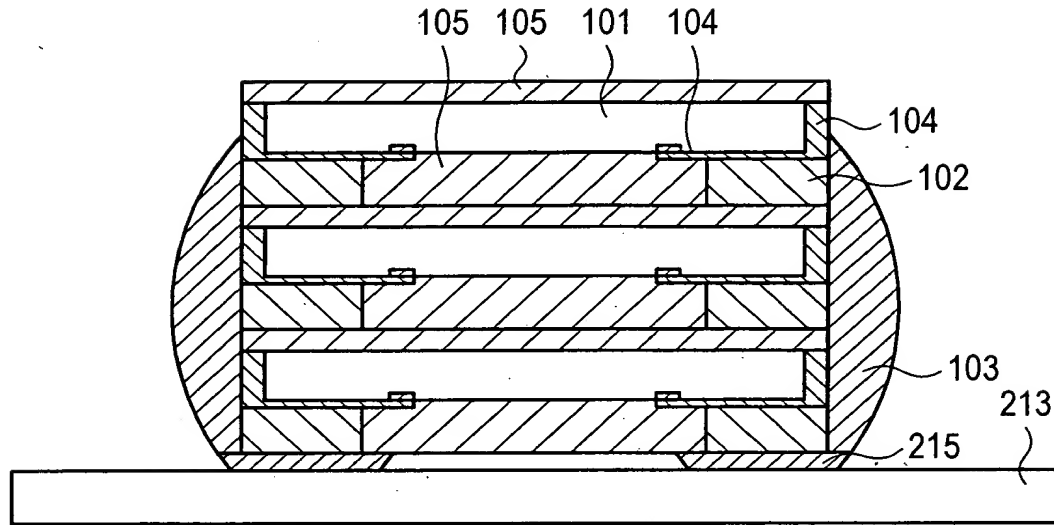


FIG.20

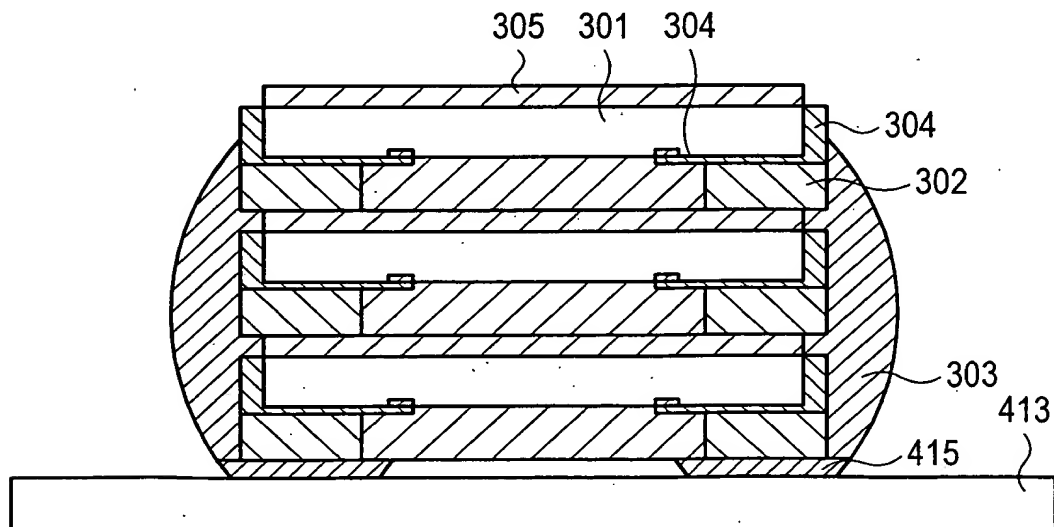


FIG.21

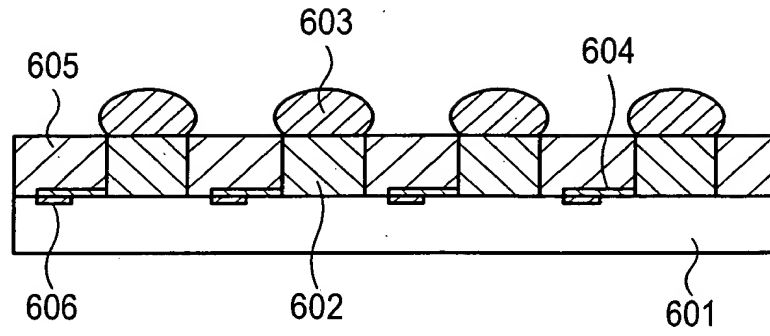


FIG.22

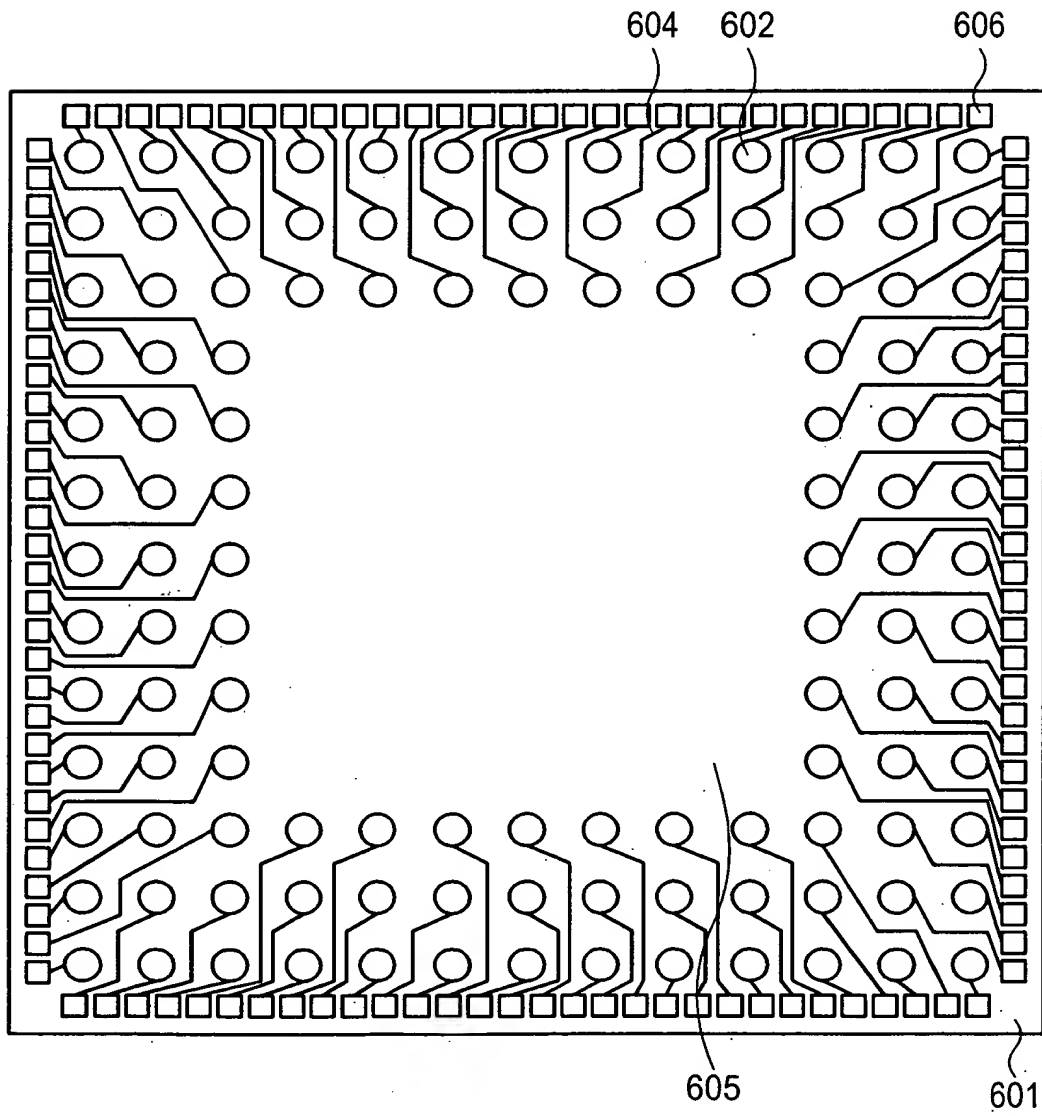


FIG.23(a)

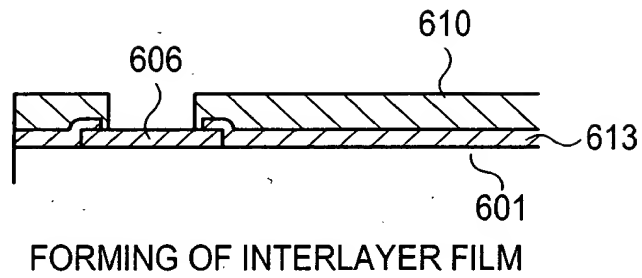


FIG.23(b)

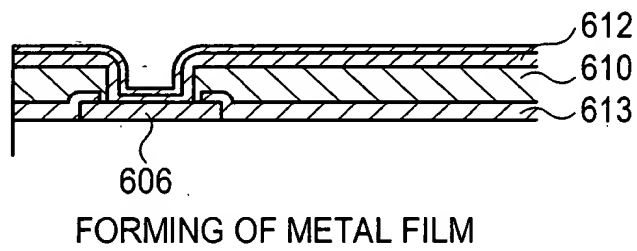


FIG.23(c)

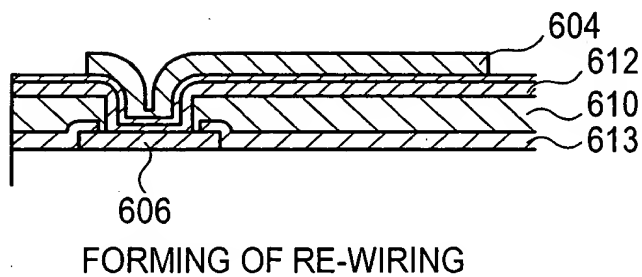
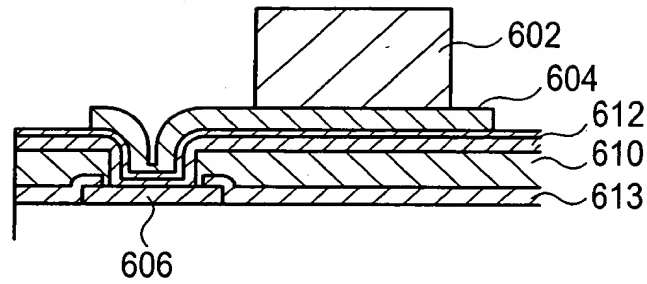
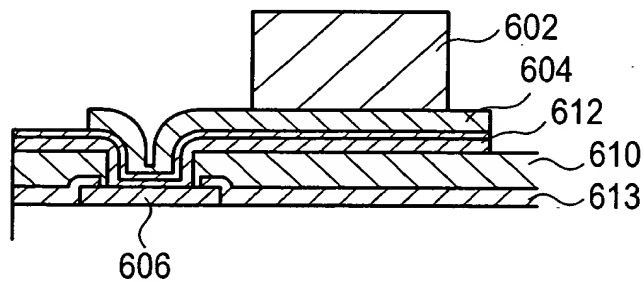
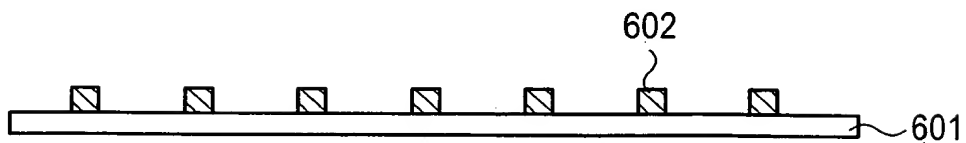


FIG.23(d)

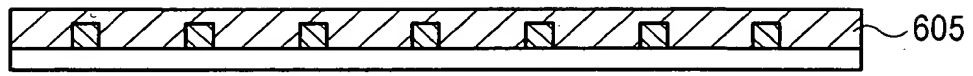
FORMING OF Cu POST

**FIG.23(e)**REMOVAL OF UNNECESSARY
METAL FILM**FIG.24(a)**

FORMING OF Cu POST



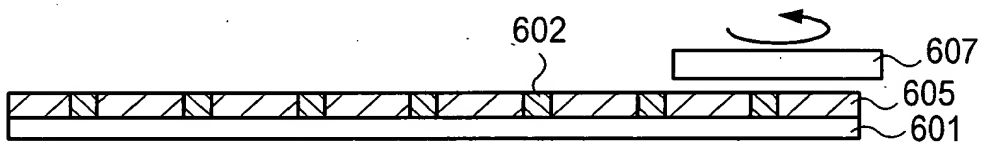
FIG.24(b)



SEALING WITH RESIN



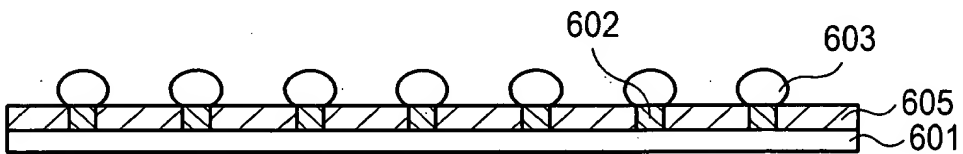
FIG.24(c)



POLISHING OF SURFACE



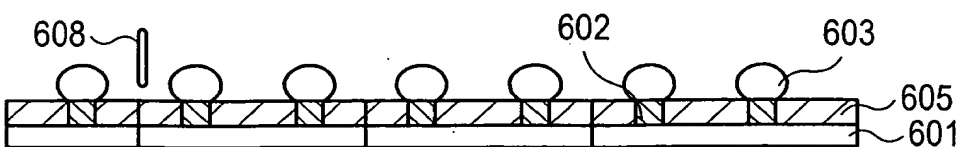
FIG.24(d)



FORMING OF TERMINAL



FIG.24(e)



DICING

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FIG.25

